

IN THE CLAIMS:

Listing of the claims:

1-51. (Canceled)

62 52. (Currently Amended) A socket contact formation process, comprising:

forming a contact head from a conductive material as at least one member of a socket contact having at least two members forming portions thereof;

forming a contact body from a semiconductive material configured to be electrically conductive as a member of a socket contact having at least two members forming portions thereof;

and

joining said contact head and said contact body forming a socket contact having at least two members forming portions thereof.

53. (Currently Amended) The process in claim 52, wherein:

said [step of] forming a contact head comprises stamping a metal element as at least one member of a socket contact having at least two members forming portions thereof;

said [step of] forming a contact body comprises etching silicon as at least one member of a socket contact having at least two members forming portions thereof; and

said [step of] joining said contact head and said contact body further comprises adhering said contact head onto said contact body forming a socket contact having at least two members forming portions thereof.

54. (Currently Amended) The process in claim 52, wherein said [step of] joining said contact head and said contact body further comprises depositing a metal over a silicon surface for a socket contact having at least two members forming portions thereof.

55-62. (Canceled)